



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-08-08
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS20150CFP	HTUI*Z11P02R	A	SHENZHEN B/E	2016-08-08
Amount		UoM	Unit type	ST ECOPACK Grade
1900.00		mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
NAC	NAC	NAC		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10.2-16.15-4.5	3	THROUGH HOLE	
Comment	TO 220 ISOL FULL PACK 0.5 AB			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HTUI*211P02R					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	7.040	mg	supplier	die	Silicon (Si)	7440-21-3		6.622	mg	940625	3485
				supplier	metallization	Aluminium (Al)	7429-90-5		0.274	mg	38920	144
				supplier	metallization	Titanium (Ti)	7440-32-6		0.006	mg	854	3
				supplier	metallization	Tungsten (W)	7440-33-7		0.010	mg	1420	5
				supplier	metallization	Nickel (Ni)	7440-02-0		0.030	mg	4261	16
				supplier	Passivation	Silicon Oxide	7631-86-9		0.040	mg	5682	21
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	426	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.010	mg	1420	5
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.045	mg	6392	24
				supplier	alloy	Copper (Cu)	7440-50-8		604.469	mg	984275	318142
Leadframe	Copper & its alloys	614.126	mg	supplier	alloy	Iron (Fe)	7439-89-6		0.278	mg	453	146
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.508	mg	827	267
				supplier	metallization	Nickel (Ni)	7440-02-0		8.816	mg	14355	4640
				supplier	metallization	Phosphorus (P)	12185-10-3		0.055	mg	90	29
Soft solder	Solder	6.365	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high mel	6.079	mg	955067	3199
				supplier	solder	Silver (Ag)	7440-22-4		0.159	mg	24980	84
				supplier	solder	Tin (Sn)	7440-31-5		0.127	mg	19953	67
Bonding wires	Other inorganic materials	4.706	mg	supplier	wire	Aluminium (Al)	7429-90-5		4.706	mg	1000000	2477
Encapsulation	Other Organic Materials	1261.897	mg	supplier	mold compound	Quartz	14808-60-7		883.328	mg	700000	464909
				supplier	mold compound	Silica, vitreous	60676-86-0		94.642	mg	75000	49812
				supplier	mold compound	Epoxy resin	25068-38-6		176.666	mg	140000	92982
				supplier	mold compound	phenol resin	29690-82-2		88.333	mg	70000	46491
				supplier	mold compound	metal hydroxide	21645-51-2		12.619	mg	10000	6642
				supplier	mold compound	carbon black	1333-86-4		6.309	mg	5000	3321
Connections coating	Solder	5.866	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		5.866	mg	1000000	3087